

SID

Factory: Rot am See

Article:

503

ML4

Provided:

Kracht, Enrico

Customer:

Date:

29.07.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	A00 B00
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	306		2	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		4	
C-RS-FR4-DS-1.20mm-070+070-TG150-HF	50200955	70	L2	5	
		1060			
		70	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	309		6	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		7	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		8	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	9	

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1885 µm

Version 1.2.14.15

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